Guidelines for IC FabLab Report

- Cover with group names and responsibility
- Acknowledgement
- Abstract
- Chapter 1: Technical Background
  - Introduction
  - Device Physics
  - Process Considerations
  - Basic NMOS Processing
  - Processing & Device Modeling –T-SUPREM & MEDICI
  - Device Characteristics & Testing Techniques
- Chapter 2: Processing Procedures
  - Detailed process flows with comments
  - Inspection results with photos
- Chapter 3: Electrical Test Results and Discussions
  - I-V, C-V, Device variations, etc., with tables/plots
- Chapter 4: Summary & Conclusions
- References & Appendix

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